

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>ZHITANG SONG</td><td>08/10/2011</td></tr><tr><td>LIANGCAI WU</td><td>08/10/2011</td></tr><tr><td>SONGLIN FENG</td><td>08/10/2011</td></tr></tbody></table>		Name	Execution Date	ZHITANG SONG	08/10/2011	LIANGCAI WU	08/10/2011	SONGLIN FENG	08/10/2011
Name	Execution Date								
ZHITANG SONG	08/10/2011								
LIANGCAI WU	08/10/2011								
SONGLIN FENG	08/10/2011								
RECEIVING PARTY DATA									
Name:	SHANGHAI INSTITUTE OF MICROSYSTEM AND INFORMATION TECHNOLOGY, CHINESE ACADEMY OF SCIENCES								
Street Address:	No. 865, Changning Road, Changning District								
City:	Shanghai								
State/Country:	CHINA								
Postal Code:	200050								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13202955</td></tr></tbody></table>		Property Type	Number	Application Number:	13202955				
Property Type	Number								
Application Number:	13202955								
CORRESPONDENCE DATA									
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Ming Chow								
Total Attachments: 2 source=assignment_CNJZM0629#page1.tif source=assignment_CNJZM0629#page2.tif									

OP \$40.00 13202955

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PATENT
REEL: 026794 FRAME: 0168

ASSIGNMENT DEED

This assignment agreement is applicable to an invention entitled (invention title) PHASE CHANGE MEMORY STRUCTURE HAVING LOW-K DIELECTRIC HEAT-INSULATING MATERIAL AND FABRICATION METHOD THEREOF

This PATENT RIGHT referred to in this agreement is (check one):

☒ a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Agreement.

☐ U.S. Patent Application Serial No. _____, filed on _____.

☐ U.S. patent No. _____, issued on _____.

The PATENT RIGHT assigned under this agreement is:

☒ U.S. Patent rights only

☐ worldwide Patent rights (the assignee shall have the right to claim the benefit for the filing date of any U.S. Patent Application identified above).

The ASSIGNOR(S) referred to in this agreement is (or are):

ZHITANG SONG (full name of first assignor)

No.865,Changning Road,Changning District,Shanghai-200050,China (address)

LIANGCAI WU (full name of second assignor)

No.865,Changning Road,Changning District,Shanghai-200050,China (address)

SONGLIN FENG (full name of third assignor)

No.865,Changning Road,Changning District,Shanghai-200050,China (address)

The ASSIGNEE referred to in this agreement is:

SHANGHAI INSTITUTE OF MICROSYSTEM AND INFORMATION TECHNOLOGY, CHINESE ACADEMY OF SCIENCES

(full name of first assignee)

No.865,Changning Road,Changning District,Shanghai-200050,China (address)

Is (check one): ☐ an individual

☐ a partnership

☒ a Corporation of CHINA

(State or Country)

PATENT

REEL: 026794 FRAME: 0169

ASSIGNMENT DEED

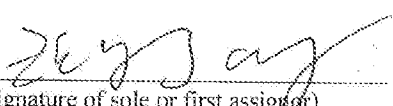
The ASSIGNOR(S), in consideration of \$1.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE, their successors and assigns:

the full and exclusive right to the invention;

an equal interest in and to the entire right and title, and interest in and to the PATENT RIGHTS in the invention, all continuations, divisionals, re-issues, and re-examination patents and patent applications; and the right to claim priority under 35 U.S.C. 119, based on any earlier foreign applications for this invention.

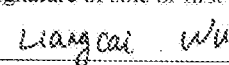
As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Director of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(S) as the ASSIGNEE(S) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(S), their successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE(S), or their representatives, and facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(S), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(S), their successors and assigns, to obtain an enforced proper protection for said invention.


(Signature of sole or first assignor)

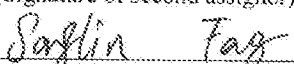
2011-08-10

(Date)


(Signature of second assignor)

2011-08-10

(Date)


(Signature of third assignor)

2011-08-10

(Date)